## Circuit Protector Elements

# **UNHZ201**

### **Circuit Protector Elements**

For overcurrent protection

#### Features

- Sharp cutoff characteristics and low voltage drop
- Flame retardant package and low heat generation, high density mounting is possible.

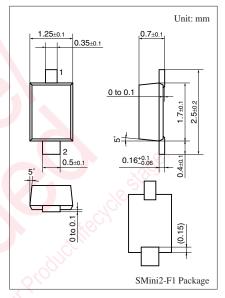
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Operating ambient temperature	T <sub>opr</sub>	-55 to +125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

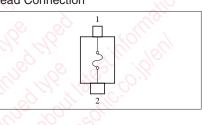
Parameter	Min	Тур	Max	Unit
Rated voltage		50		v
Rated current		0.7		A
Internal Resistance	70	93	116	mΩ
Cutoff current *		1.4		A

Note) \*: Measurement condition of cutoff current shall be at  $T_a = 25^{\circ}C$ , t = 1 s Tolerance of cutoff current shall be  $\pm 20\%$ 



Marking Symbol: H1

#### Lead Connection

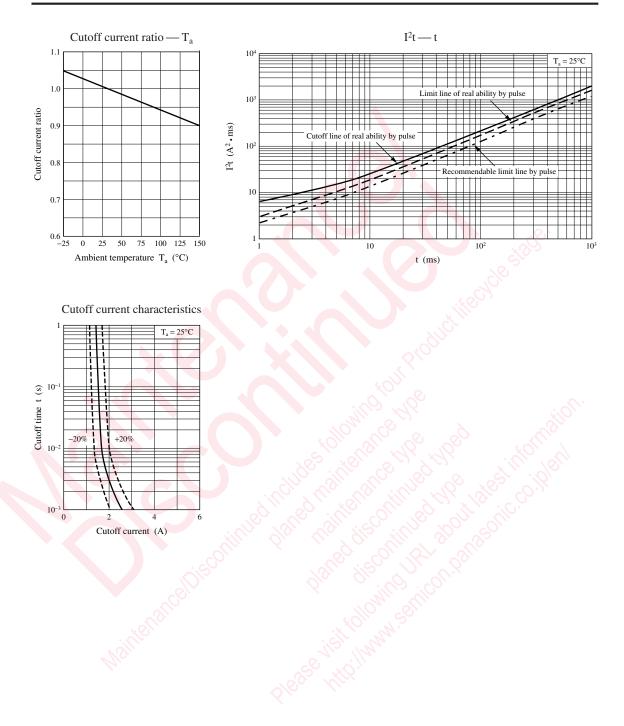


#### Usage Notes

- Package shall be overheated and dangerous for overcurrent.
- This device should be used only to the secondary circuit. Package will be damaged for added overpower.
- This device is not electrical fuse legally. Please draw a clear line between electrical fuse from this device.

**Panasonic** 

#### UNHZ201



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